Advanced Packaging Update:
Market and Technology Trends

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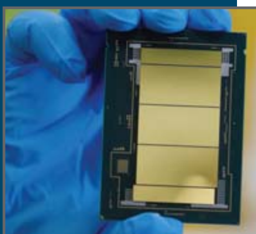

This issue of the Advanced Packaging Update features an analysis of market trends for AI applications with a forecast for training and inferencing packages. High-performance advanced packaging offerings from major foundries and OSATs are compared. OSATs financials are discussed. A special section is devoted to government investments in the semiconductor industry. An update on the build-up substrate market supply and demand is presented. An analysis of the thermo-compression bonder equipment market is provided.

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TechSearch INTERNATIONAL
4801 Spicewood Springs Road • Suite 150
Austin, Texas 78759
Tel: 512-372-8887 • Fax: 512-372-8889
tsi@techsearchinc.com • www.techsearchinc.com

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